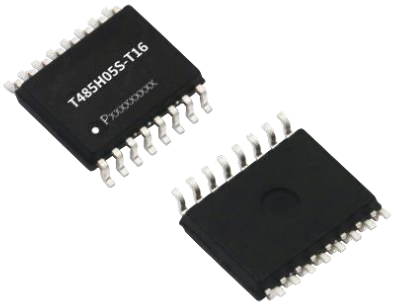
Descriptions

SOIC16 package isolated RS485 Half Duplex Transceiver



RoHS

Features

- Ultra-small, ultra-thin, chip scale SOIC16 package
- Compliant with TIA/EIA-485-A standard
- Wide power supply range: 3.0-5.5V
- Integrated efficient isolation power supply with overload and short circuit protection
- I/O power supply range supports 3.3V and 5V microprocessors
- High isolation to 5000Vrms
- Bus-Pin ESD protection up to ±8kV(HBM)/±4kV(Contact)
- Baud rate up to 20Mbps
- High common mode transient immunity 180kV/μs (Typical)
- Nanosecond level communication delay
- 1/8 unit load–up to 256 nodes on a bus
- Bus fail-safe
- Bus driver short circuit protection
- Industrial operating ambient temperature range: -40℃ to +125℃

Applications

- Industrial Automation
- Building Automation
- Smart Electricity Meter
- Remote Signal Interaction
- Transmission

Functional Description

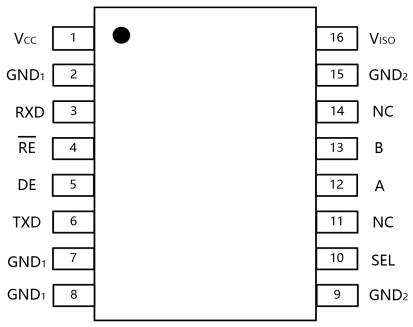
T485H05S-T16 is a half-duplex enhanced transceiver designed for RS-485/RS-422 data bus networks, has high electromagnetic immunity and low radiation characteristics which is fully compliant with TIA/EIA-485-A standard and is suitable for data transmission of up to 20Mbps. Receivers have an exceptionally high input impedance, which places only 1/8 of the standard load on a shared bus and up to 256 transceivers.

T485H05S-T16 device has high insulation capacity, which helps to prevent noise and surges on the data bus or other circuits from entering the local grounding terminal, thereby interfering or damaging sensitive circuits. High CMTI capability can ensure the correct transmission of digital signals. On the basis of traditional IC, the focus is on strengthening the reliability design of A, B pins, including driver overcurrent protection and enhanced ESD design. The A, B ports can withstand ESD up to ±8kV (HBM) and ±4kV (contact discharge).

Contents

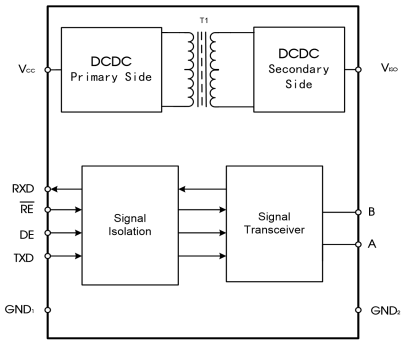
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Pin Connection



Note: All GND_1 pins are internally connected;
All GND_2 pins are internally connected.

Internal Block Diagram



Function Table

Letter	Description
H	High-Level
L	Low-Level
X	Unrelated
Z	High Impedance

Table 1. Driver Function table

TXD	DE	Output	
		A	B
H	H	H	L
L	H	L	H
X	L	Z	Z

Table 2. Receiver Function table

VID = (VA - VB)	$\overline{RE}$	RXD
-0.01 V ≤ VID	L	H
-0.21 V < VID < -0.01V	L	Uncertainty
VID ≤ -0.21 V	L	L
X	H	Z
Open circuit	L	H

Note:
① When driving status, the DE and $\overline{RE}$ pins are connected to a high level;
② When receiving status, the DE and $\overline{RE}$ pins are connected to a low level.

Pin Descriptions

Pin Number	Pin Name	Pin Functions
1	V_{CC}	Power supply. By using 0.1uF and 10uF ceramic capacitance ground (GND_1).
2	GND_1	Logic side reference ground.
3	RXD	Receiver Output Data.
4	$\overline{RE}$	Receiver enable input. When $\overline{RE}$is low, if (A-B)≥-10mV, then RXD = high. if (A-B)≤-210mV, then RXD = low.
5	DE	Driver enable input. When DE is high, outputs are enabled. When DE is low, outputs are high impedance. Drive DE low and $\overline{RE}$ high to enter shutdown mode.
6	TXD	Driver Input.
7	GND_1	Logic side reference ground.
8	GND_1	Logic side reference ground.
9	GND_2	Bus side reference ground.
10	SEL	Isolation power supply V_{ISO} output voltage selection pin.
11	NC	No Function Pin, Dangling.
12	A	RS485 Bus A wire pin.
13	B	RS485 Bus B wire pin.
14	NC	No Function Pin, Dangling
15	GND_2	Bus side reference ground. The pin needs to be connected to pin9 in application.
16	V_{ISO}	Isolate power output. Close to this pin, 0.1uF and 10uF ceramic capacitors must be connected to the bus side reference ground (GND_2).

Note: When SEL is connected to V_{ISO}, V_{ISO}=5V. When SEL is connected to GND_2 or suspended, V_{ISO}=3.3V. When the V_{CC} voltage is 3.3V, SEL can only be grounded or suspended; When the V_{CC} voltage is 5V, SEL is not restricted.

Absolute Maximum Ratings

Parameters	Unit
Supply voltage V_{CC}	-0.5V to +6V
Output voltage Vin	-0.5V to V_{CC}+0.5V
Output current I_O	-10mA to +10mA
Junction temperature T_J	< 150℃
Operating Temperature Range	-40℃ to +125℃
Storage Temperature Range	-65℃ to +150℃

Important:

①Exposure to absolute maximum rated conditions for an extended period may severely affect the device reliability, and stress levels exceeding the "Absolute Maximum Ratings" may result in permanent damage. All voltage values are based on the reference ground(GND) maximum voltage not exceeding 6V;

②General test conditions: Free-air, normal operating temperature range (Unless otherwise specified).

Recommended work parameters

Symbol	Conditions	Min.	Typ.	Max.	Unit
V_{CC}	Power supply voltage	3.0	3.3/5.0	5.5	V
V_I	Voltage at pins A and B	-7	--	12	
V_{IH}	High-level input voltage	2	5.0	5.5	
V_{IL}	Low-level input voltage	0	--	0.8	
T_A	Working environment temperature	-40	25	125	℃
DR	Transfer speed	--	--	20	MbpS

Electrical Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Driver						
$\|V_{OD3}\|$	Absolute value of differential output voltage	No load, SEL is low level or dangling	3.0	--	--	V
		No load, SEL is High level	4.5	--	--	
		RL=54Ω, SEL is low level or dangling	1.5	--	--	
		RL=54Ω, SEL is High level	1.5	--	--	
ΔV_{OD}	$\Delta\|V_{OD}\|$ for complementary output states	No load, Figure 2	-0.2	--	0.2	
V_{IH}	High level output voltage	TXD, DE	2	5	5.5	
V_{IL}	Low level output voltage	TXD, DE	0	--	0.8	
I_{IH}	Input high-level leakage current	TXD, DE	--	--	20	uA
I_{IL}	Input low-level leakage current	TXD, DE	-20	--	--	
I_A	Driver short-circuit current		--	±150	±250	mA
CMTI	Common mode transient immunity	V_{CM} = 1200V; Figure 7	--	180	--	kV/μS

Receiver						
$V_{IT(+)}$	Positive differential input threshold voltage	$-7\ V \le V_{CM} \le +12\ V$	--	--	-10	mV
$V_{IT(-)}$	Negative differential input threshold voltage	$-7\ V \le V_{CM} \le +12\ V$	-210	--	--	
V_{hys}	Hysteresis voltage ($V_{IT+} - V_{IT-}$)	$-7\ V \le V_{CM} \le +12\ V$	--	30	--	
V_{OH}	RXD high level output voltage		Vcc – 0.4	4.8	--	V
V_{OL}	RXD low level output voltage		0	0.2	0.4	
V_{IH}	High level output voltage	$\overline{RE}$	0.7VCC	--	--	
V_{IL}	Low level output voltage	$\overline{RE}$	--	--	0.3VCC	
I_{IH}	Input high-level leakage current	$\overline{RE}$	--	--	20	uA
I_{IL}	Input low-level leakage current	$\overline{RE}$	-20	--	--	
R_{ID}	Differential input resistance(A, B)	$-7\ V \le V_{CM} \le +12\ V$	96	--	--	kΩ
Power supply and safeguard characteristic						
V_{ISO}	Isolated power output voltage	V_{CC}=5V or 3.3V, SEL is low level or dangling	3.1	3.3	3.5	V
		V_{CC}=5V, SEL is High level	4.8	5.0	5.30	
I_{CC}	Logic side power supply current	A and B no load, SEL is low level or dangling	--	14	25	mA
		A and B no load, SEL is High level	--	17	25	
		Maximum operating current, SEL is low level or dangling	--	87	160	
		Maximum operating current, SEL is High level	--	141	200	
ESD	HBM Mode	A, B ports	--	--	±8	kV
	Contact discharge mode	A, B ports	--	--	±4	
V_{IO}	Insulate voltage	$V_{TEST}=V_{IO}$, t=60s $V_{TEST}=1.2xV_{IO}$, t=1s(100%production test)	--	--	5000	VAC
R_{IO}	Insulate impedance	500VDC	1	--	--	GΩ

Transmission Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
-	Data rate	Duty 40% ~ 60%	--	--	20	Mbps
T_{PHL}, T_{PLH}	Driver propagation delay	R_L=54Ω,	--	45	80	ns
$\lvert T_{PHL}-T_{PLH}\rvert$	Driver skew ($\lvert T_{PHL} - T_{PLH}\rvert$)	$C_{L1}=C_{L2}$=50pF	--	--	25	
T_R, T_F	Driver rise/fall time	Figure 3	--	8	25	
t_{PZH}/ t_{PZL}	Drive off enable propagation delay	R_L=54Ω,	--	--	110	

t_{PHZ}/ t_{PLZ}	Drive Enable Propagation Delay	C_{L1}=C_{L2}=50pF Figure 6	--	--	110	
T_{PHL}, T_{PLH}	Receiver propagation delay	R_L=54Ω	--	88	150	
$\|T_{PHL}-T_{PLH}\|$	Receiver propagation delay	C_L = 15pF, Figure 4	--	--	25	
T_R, T_F	Receiver rise/fall time		--	2	10	
t_{PLH}	Receive off enable propagation delay, Output low-level to high-level time	R_L=54Ω C_{L1}=C_{L2}=50pF	--	--	110	
t_{PHL}	Receive enable propagation delay time, Output high-level to low-level time	Figure 4 Figure 5	--	--	110	

Physical Specifications

Parameters	Value	Unit
Weight	0.4(Typ.)	g

Parameter testing circuit

Note: Test condition load capacitance includes test probe and fixture parasitic capacitance (no special instructions). The rising and falling edges of the test < 6ns. frequency 100kHz. duty50%. resistance Z_O = 54Ω.

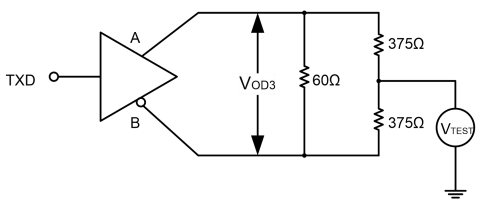


Figure 1. Common mode output test circuit

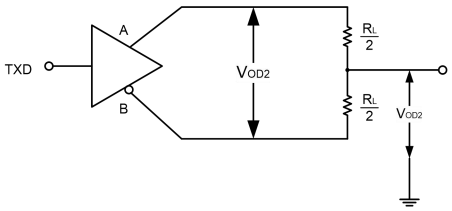
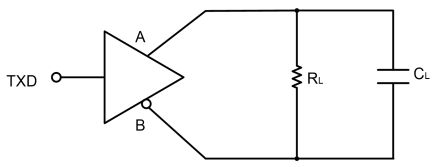
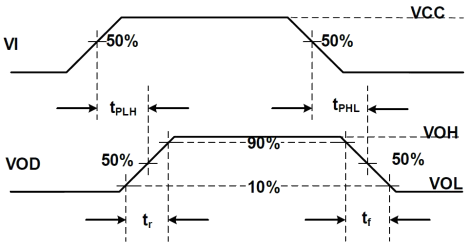


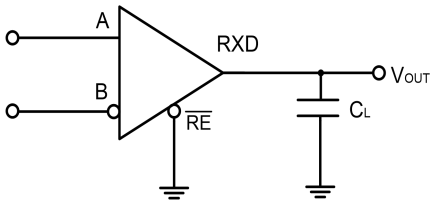
Figure 2. Differential output test circuit

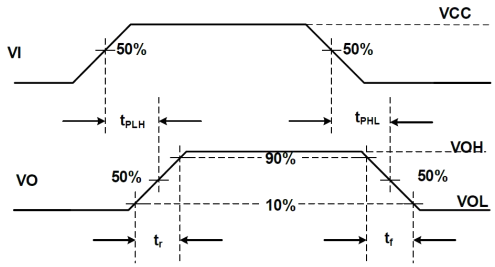




Note: CL includes parasitic capacitance of fixtures and instruments

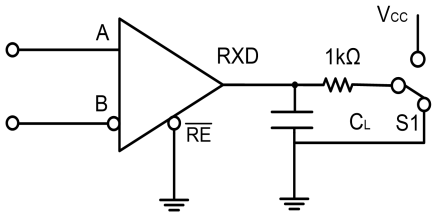
Figure 3. Drive propagation delay test circuit and wave forms





Note: CL includes parasitic capacitance of fixtures and instruments

Figure 4. Receiver propagation delay test circuit and wave forms



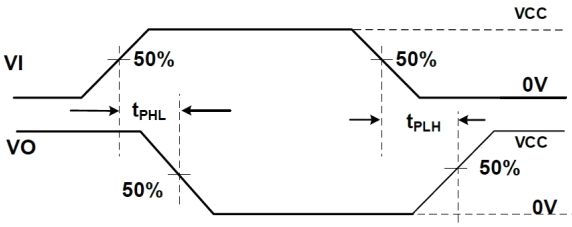
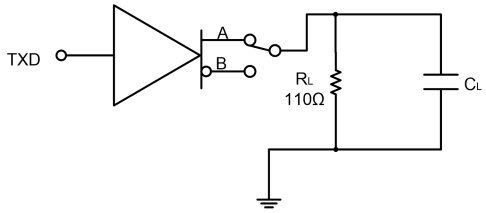
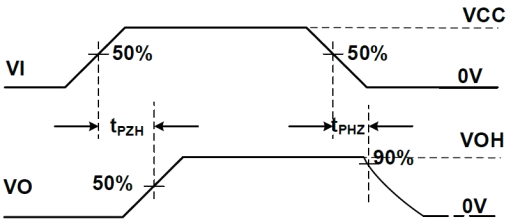
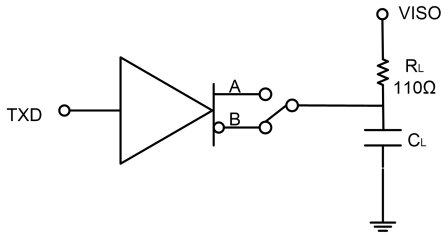
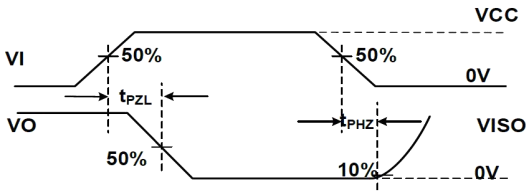


Figure 5. Receiving on/off time test circuit









Note: CL includes parasitic capacitance of fixtures and instruments

Figure 6. Driver On/Off Time Test Circuit

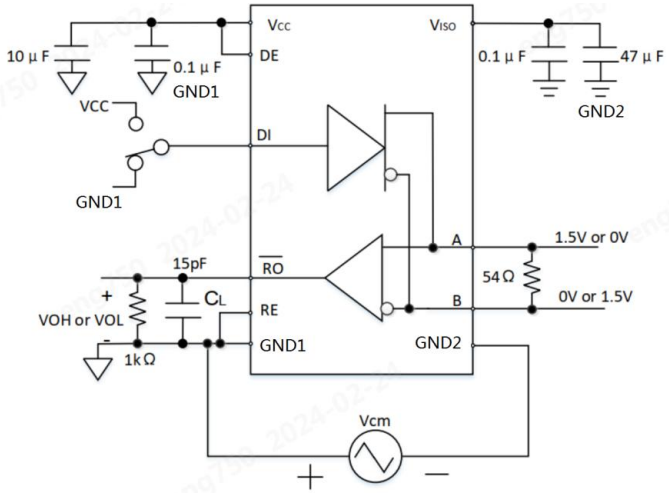


Figure 7. CMTI Test Circuit

Detailed Description

T485H05S-T16 is a half-duplex enhanced RS-485 isolated transceiver with isolated power supply. In addition to an isolated power supply, each transceiver contains a drive and a receiver. The transceiver has a standby bus failure protection function to ensure that the receiver output is high when the receiver input is open, short, or when the bus is idle.equipped with failure safety, overcurrent protection, and overheating protection functions.

Bus failure protection: When the receiver input is short circuited or open, and all drivers hanging on the terminal matching transmission line are disabled (idle), the T485H05S-T16 product can ensure that the receiver output logic is high. This is achieved by setting the input threshold of the receiver to -210mV and -10mV, respectively. If the input voltage (A-B) of the differential receiver is ≥ -10mV, RO is the logic high level; If the voltage (A-B) is ≤ -210mV, RO is the logic low level. When all transmitters connected to the terminal matching bus are disabled, the differential input voltage of the receiver will be pulled to 0V through the terminal resistor. Based on the receiver threshold, a logic high level with a minimum noise tolerance of -10mV can be achieved- The threshold voltage from -210mV to -10mV is in accordance with EIA/TIA-485 standards.

The bus load capacity (256 point): standard RS485 receiver input impedance is defined as 12kΩ (unit load). A standard RS485 driver can drive at least 32 load units. T485H05S-T16 bus receiver designed by 1/8 unit load, the input impedance is greater than 96kΩ. As a result, the bus allows access to more transceivers (up to 256). T485H05S-T16 can also be mixed with the standard RS485 transceiver with 32 unit loads (cumulative receiver load cannot exceed 32 units).

Application Circuit

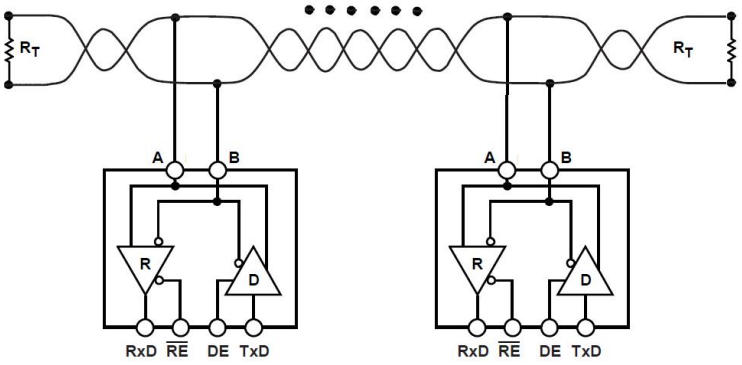


Figure 8.Typical application circuit (half-Duplex Network Topology)

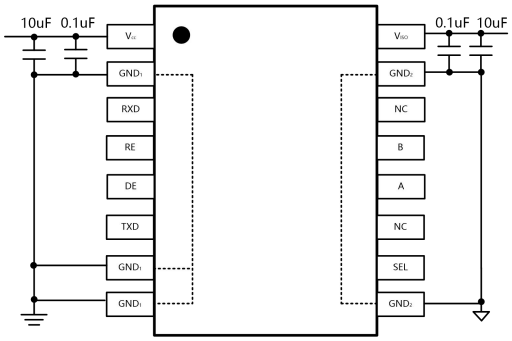
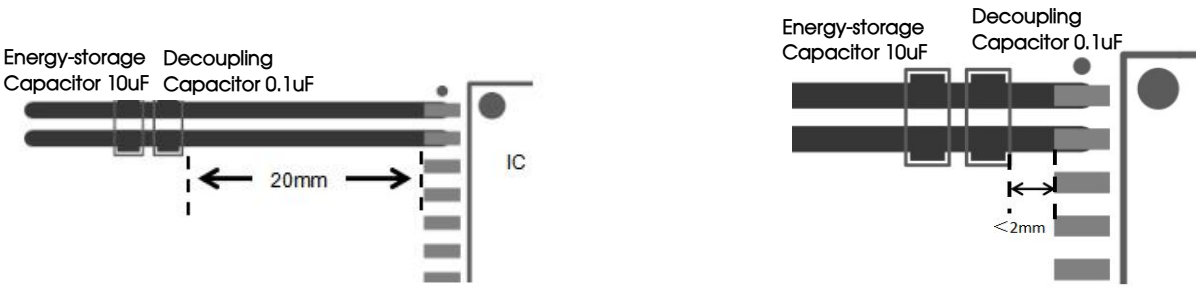


Figure 9. Typical Application Diagram

PCB design description:

1. The decoupling capacitors and energy storage capacitors of VCC and GND1, VISO and GND2 should be placed as close to the chip pins as possible to reduce the loop area and parasitic inductance of PCB wiring. Generally, it should be controlled within 2mm. The decoupling capacitor is placed near the chip, and the energy storage capacitor is placed on the outside. As shown in Figure 10-1.



Not recommended

Recommend

Figure 10-1

2. When wiring, the power line width should be designed to be at least 0.5mm.

3. When it is necessary to place vias in the power supply line and ground wire, the position of the vias should be on the outer side of the capacitor relative to the chip pins, rather than between the capacitor and the chip, as shown in Figure 10-2 to reduce the impact of parasitic inductance in the vias.



Not recommended

Recommend

Figure 10-2

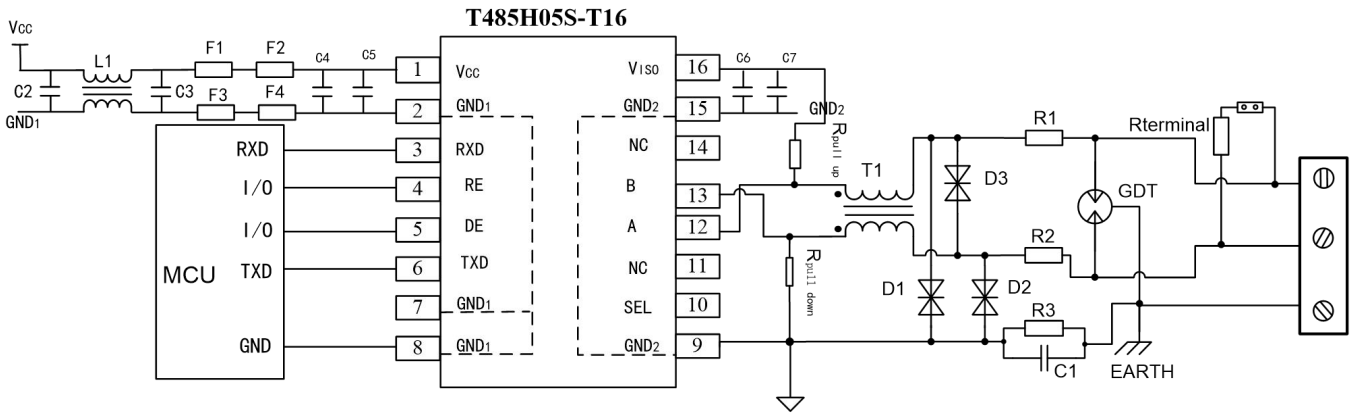


Figure11. Port protection circuit for harsh environments

Recommended components and values:

Component	Recommended part, value	Component	Recommended part, value
R3	1MΩ	R1, R2	2.7Ω/2W
C1	1nF, 2kV	D1, D2	SMBJ6.5CA
T1	ACM2520-301-2P	D3	SMBJ6.5CA
GDT	B3D090L	$R_{terminal}$	120Ω

C2,C3	10uF/16V (SMD ceramic capacitor)	C5.C6	0.1uF/16V
C4,C7（Must add）	10uF/16V (SMD ceramic capacitor)	L1	EFL2D-0.5-080
F1,F2,F3,F4	BA0805-102T		

To improve the system's EMI performance, you can add common-mode inductors and beads at the VCC-GND front end of the module.

As the modules internal A / B lines come with its own ESD protection, which generally satisfy most application environments without the need for additional ESD protection devices. For harsh and noisy application environments such as motors, high voltage/current switches, lightning and similar however, we recommended that the user protects the module's A / B lines with additional measures and external components such as TVS tube, common mode inductors, Gas discharge tube, shielded twisted pair of wires with the same single network Earth point. Figure 11 shows our recommended circuit diagram for such type of applications with components and values given in the table above. This recommendation is for reference only and may have to be adapted accordingly with appropriate component values in order to match the actual situation and application.

Note: Select the $R_{terminal}$ according to the actual application.

Recommendations

① The product does not support hot-plugging.

② TXD external inputs should have pull-up resistors added as appropriate if drive capability is insufficient.

③ In order to maintain the bus idle stability, it is necessary to pull up A to VISO and pull down B to GND2 in at least one node at the bus end.

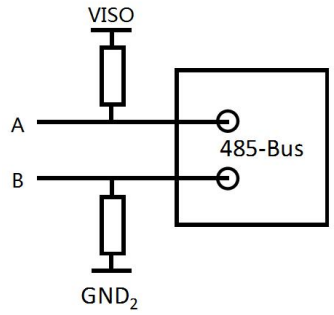


Figure 12. Typical Pull-Up and Pull-Down Resistor Connections

④ DE and $\overline{RE}$ pin do not support dangling. If the pin is not access controller, the recommended by 30 kΩ pulldown resistor pins connect to GND. Keep the node in the receiving state only, not affect the bus.

⑤ DE, $\overline{RE}$, TXD pin is always not allow to set to open drain output state connect the controller, otherwise it will lead to uncertain consequences;

⑥When using it, the RXD pin should be connected to a 1kΩ-10kΩ pull-up resistor to ensure it stays high when idle, so it doesn't affect the bus.

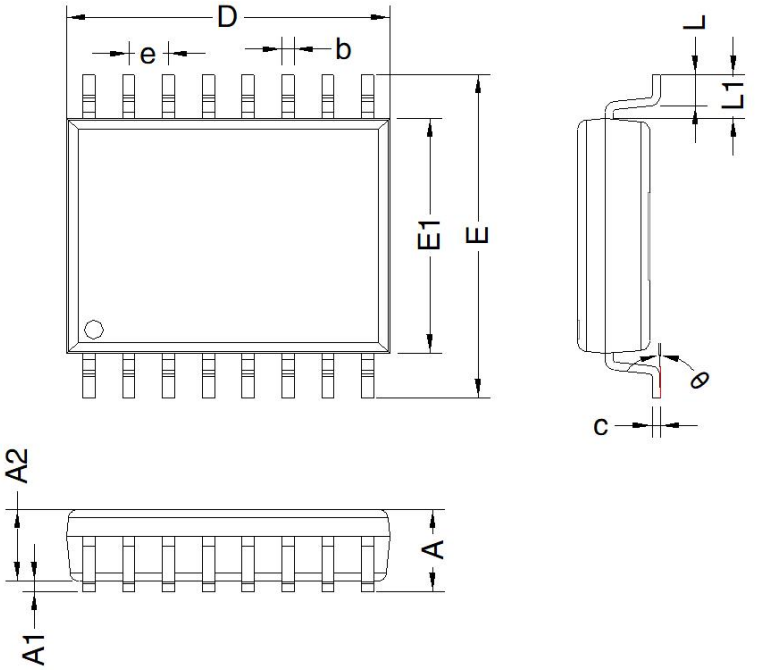
⑦When in use, if DERE is enabled high and the product is in sending mode, the RXD signal needs to be blocked and should not receive the RXD signal.

Ordering Information

Part number	Package	Number of pins	Product marking	Tape & Reel
T485H05S-T16	SOIC	16	T485H05S-T16	340/REEL

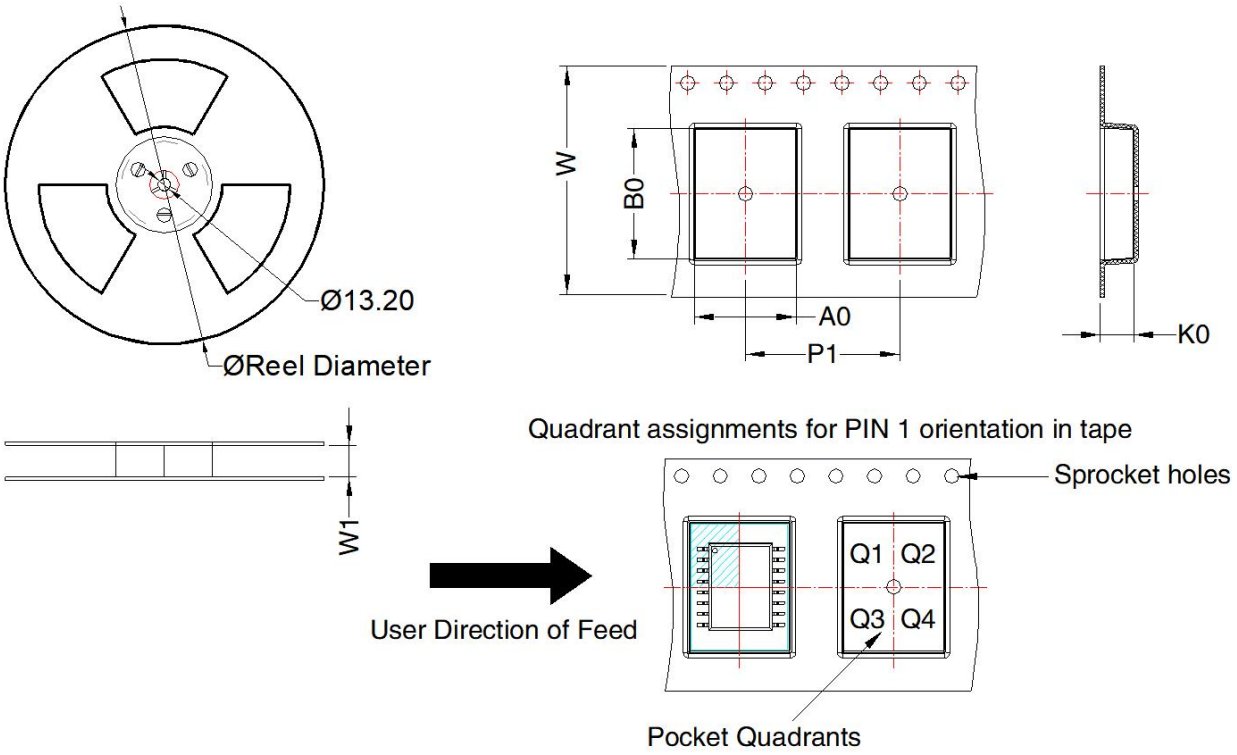
Package Information

THIRD ANGLE PROJECTION



Mark	Dimension(mm)	
	Min	Max
A	–	2.65
A1	0.10	0.30
A2	2.25	2.35
b	0.35	0.43
c	0.24	0.29
D	10.20	10.40
e	1.27 BSC	
E	10.10	10.50
E1	7.40	7.60
L	0.55	0.85
L1	1.40 BSC	
θ	0°	8°

Tape & Reel Information



Package Type	Pin	MPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SOIC16	16	340	180	16.4	10.74	10.65	3.5	16.0	16.0	Q1